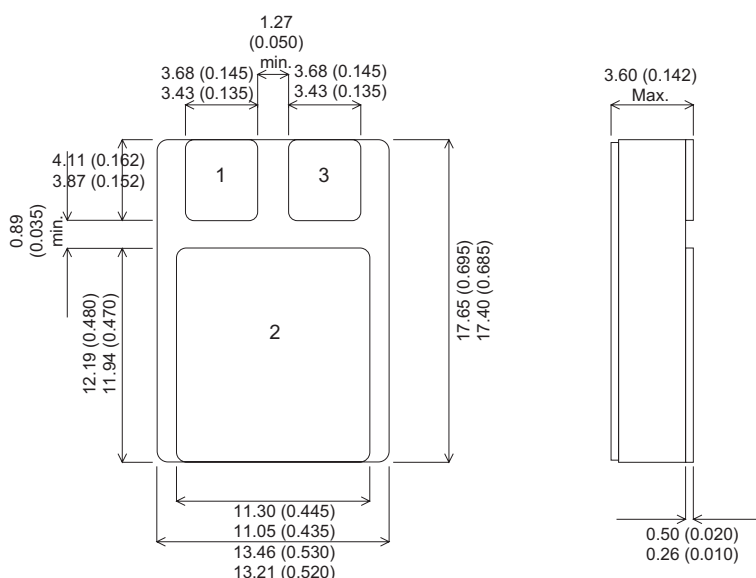


MECHANICAL DATA

Dimensions in mm (inches)


**P-CHANNEL
POWER MOSFET**

V_{DSS}	–60V
$I_{D(cont)}$	–55A
$R_{DS(on)}$	0.026Ω

FEATURES

- HERMETICALLY SEALED SMD2 CERAMIC PACKAGE
- SIMPLE DRIVE REQUIREMENTS
- SCREENING OPTIONS AVAILABLE

SMD2 (TO276-AC) Ceramic Package

PAD 1 – Source PAD 2 – Drain PAD 3 – Gate

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{DSS}	Drain – Source Voltage	–60V
I_D	Continuous Drain Current ($V_{GS} = 0$, $T_{case} = 25^{\circ}C$)	–55A
I_D	Continuous Drain Current ($V_{GS} = 0$, $T_{case} = 100^{\circ}C$)	–38.9A
I_{DM}	Pulsed Drain Current ¹	–220A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	150W
	Linear Derating Factor	1.0W/ $^{\circ}C$
E_{AS}	Single Pulse Avalanche Energy ²	820mJ
I_{AR}	Avalanche Current ¹	–55A
E_{AR}	Repetitive Avalanche Energy ¹	21.4mJ
dv/dt	Peak Diode Recovery ³	–7.0V/ns
T_J, T_{stg}	Operating and Storage Temperature Range	–55 to +175 $^{\circ}C$
T_L	Lead Temperature 1.6mm (0.63”) from case for 10 sec.	300 $^{\circ}C$

Notes

- 1) Repetitive Rating – Pulse width limited by maximum junction temperature.
- 2) @ $V_{DD} = -25V$, $L = 0.315mH$, $R_G = 25\Omega$, $I_{AS} = -55A$, Starting $T_J = 25^{\circ}C$
- 3) @ $I_{SD} \leq -47A$, $di/dt \leq -300A/\mu s$, $V_{DD} \leq BV_{DSS}$, $T_J \leq 25^{\circ}C$

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS							
BV _{DSS}	Drain – Source Breakdown Voltage	V _{GS} = 0	I _D = −250μA	−60			V
ΔBV _{DSS}	Temperature Coefficient of Breakdown Voltage	Reference to 25°C I _D = −250μA			−0.06		V/°C
R _{DS(on)}	Static Drain – Source On–State Resistance ¹	V _{GS} = −10V	I _D = −27.5A		0.021	0.026	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS}	I _D = −250μA	−2		−4	V
g _{fs}	Forward Transconductance ¹	V _{DS} = −30V	I _{DS} = −27.5A		22		S
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = −60V				−1	μA
		V _{DS} = −48V T _C = 125°C				−10	
I _{GSS}	Forward Gate – Source Leakage	V _{GS} = −25V				−100	nA
I _{GSS}	Reverse Gate – Source Leakage	V _{GS} = 25V				100	
DYNAMIC CHARACTERISTICS							
C _{iss}	Input Capacitance	V _{GS} = 0			2800		pF
C _{oss}	Output Capacitance	V _{DS} = − 25V			1300		
C _{rss}	Reverse Transfer Capacitance	f = 1MHz			320		
Q _g	Total Gate Charge	V _{GS} = −10V			84	110	nC
Q _{gs}	Gate – Source Charge	I _D = −47A			18		
Q _{gd}	Gate – Drain (“Miller”) Charge	V _{DS} = −48V			44		
t _{d(on)}	Turn–On Delay Time	V _{DD} = −30V			50	110	ns
t _r	Rise Time	I _D = −23.5A			450	910	
t _{d(off)}	Turn–Off Delay Time	R _G = 25Ω			100	210	
t _f	Fall Time				195	400	
SOURCE – DRAIN DIODE CHARACTERISTICS							
I _S	Continuous Source Current					−55A	A
I _{SM}	Pulse Source Current ²					−220A	
V _{SD}	Diode Forward Voltage	I _S = −55A	V _{GS} = 0			−4.0	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0			130		ns
Q _{rr}	Reverse Recovery Charge	I _F = −47A	di/dt = 100A/μs		0.55		μC

- Notes**
- 1) Pulse Test: Pulse Width $\leq 300\mu s$, $\delta \leq 2\%$
 - 2) Repetitive Rating – Pulse width limited by maximum junction temperature.